$V_{DSS}$	40V
R <sub>DS(on)</sub> (Max.)	7.5mΩ
I <sub>D</sub>	±40A
$P_D$	26W

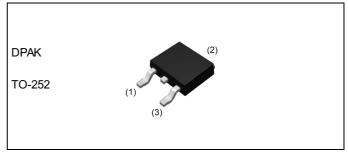
# ● Features

- 1) Low on resistance
- 2) High power package (TO-252)
- 3) Pb-free lead plating; RoHS compliant
- 4) Halogen free

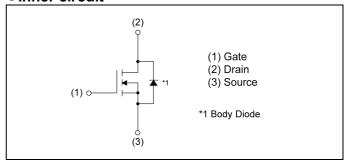
# Application

Switching

## Outline



## Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	16
	Basic ordering unit (pcs)	2500
	Taping code	TL
	Marking	RD3G400GN

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	40	V
Continuous drain current	I <sub>D</sub> *1	±40	А
Pulsed drain current	I <sub>DP</sub> *2	±80	Α
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *3	20	А
Avalanche energy, single pulse	E <sub>AS</sub> *3	3.1	mJ
Power dissipation	P <sub>D</sub> *1	26	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Parameter	Symbol	Values			Lleit
		Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	ı	4.8	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Symbol	Canditions	Values			Limit
Parameter	Symbol	Symbol Conditions Min. Typ.		Тур.	Max.	Unit
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	40	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	26.2	-	mV/°C
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V	1	1	1	μA
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	ı	ı	±500	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 1mA$	1.0	1	2.5	V
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-4.9	-	mV/°C
Static drain - source	D *4	V <sub>GS</sub> = 10V, I <sub>D</sub> = 40A	-	5.6	7.5	mΩ
on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 40A	-	7.0	9.5	11122
Gate resistance	R <sub>G</sub> f = 1MHz, open drain		-	2.0	-	Ω
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = 5V, I <sub>D</sub> = 20A	20	-	-	S

<sup>\*1</sup> Tc=25°C, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw $\leq$ 10 $\mu$ s , Duty cycle $\leq$ 1%

<sup>\*3</sup> L  $\simeq$  0.01mH, V<sub>DD</sub> = 20V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Dorameter	Cumbal	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	1410	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 20V	-	230	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	1	62	1	
Turn - on delay time	t <sub>d(on)</sub> *4	V <sub>DD</sub> ≈ 20V,V <sub>GS</sub> = 10V	1	8.2	1	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 20A	1	5.6	1	no
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 1.0\Omega$	-	41	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	6.8	-	

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Cymaele ed	Conditions		Values			l limit		
Parameter	Symbol			Min.	Тур.	Max.	Unit		
Total gate charge	O *4		V <sub>GS</sub> = 10V	-	19	-			
Total gate charge	Qg*4	$Q_g$		V <sub>DD</sub> ≃ 20V		-	9.7	-	~C
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 40A	V <sub>GS</sub> = 4.5V	-	3.7	-	nC		
Gate - Drain charge	Q <sub>gd</sub> *4				-	2.8	-		

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Symbol Conditions		Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub>	T = 25°C	1	-	21	Α
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	80	Α
Forward voltage	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = 21A	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = 40A, V <sub>GS</sub> =0V	-	21	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	di/dt = 100A/μs	-	8.8	-	nC

Fig.1 Power Dissipation Derating Curve

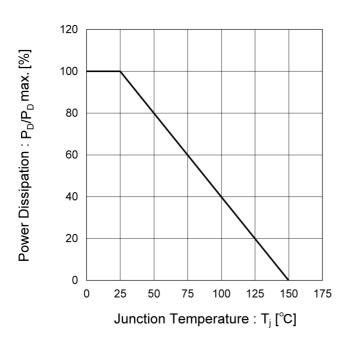
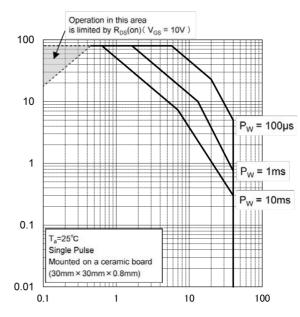


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

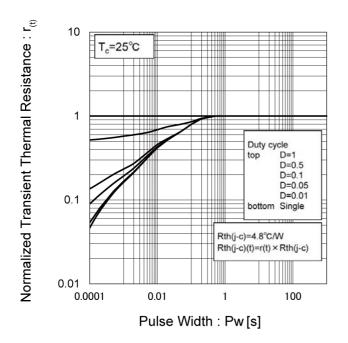
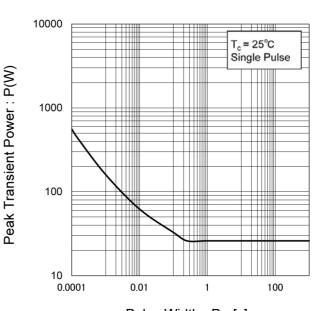


Fig.4 Single Pulse Maximum Power dissipation



Pulse Width : Pw [s]

Fig.5 Typical Output Characteristics(I)

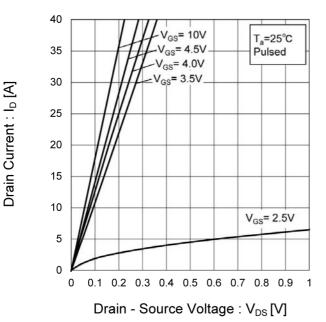
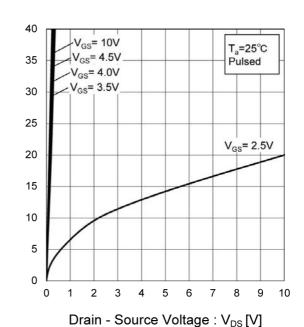


Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

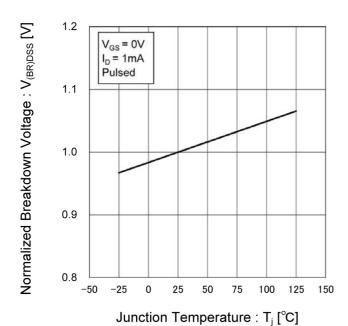


Fig.8 Typical Transfer Characteristics

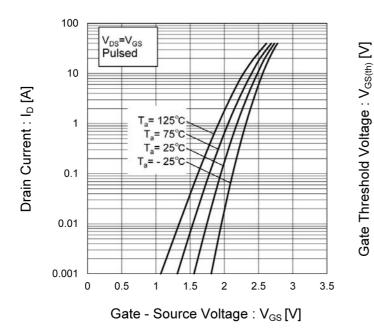


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

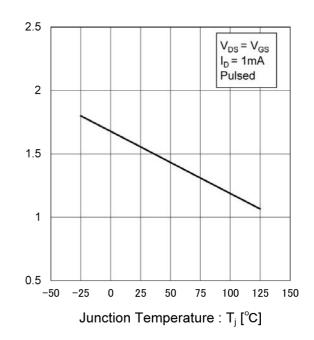


Fig.10 Forward Transfer Admittance vs.
Drain Current

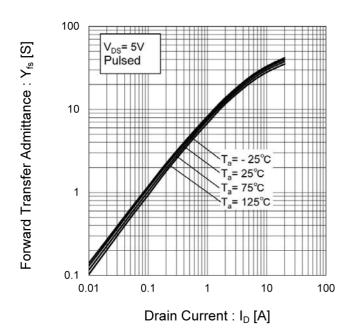


Fig.11 Drain Current Derating Curve

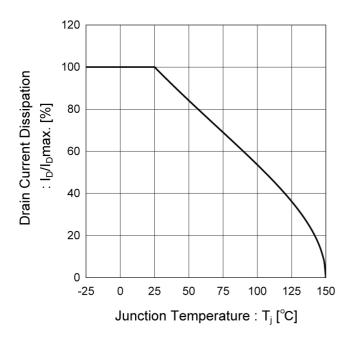


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

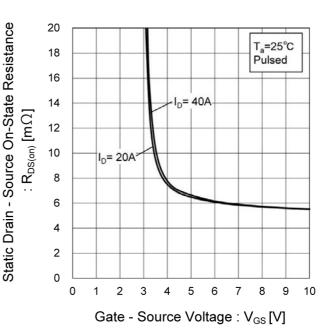


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

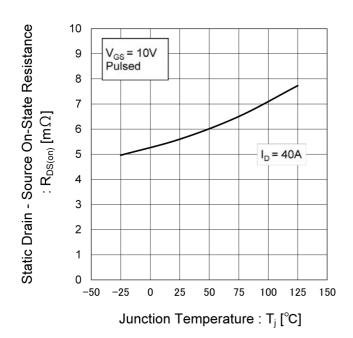


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

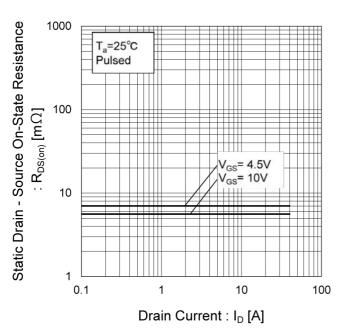


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

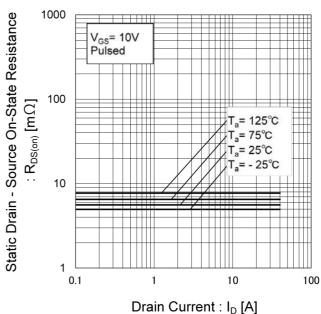


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

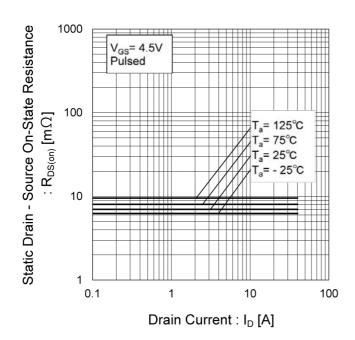


Fig.17 Typical Capacitance vs.

Drain - Source Voltage

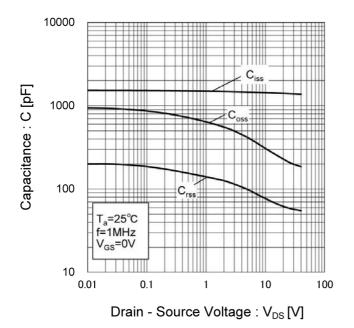


Fig.18 Switching Characteristics

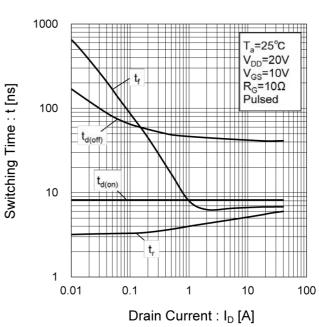


Fig.19 Dynamic Input Characteristics

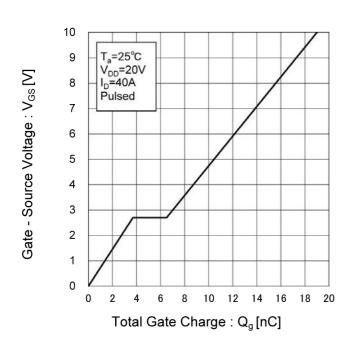
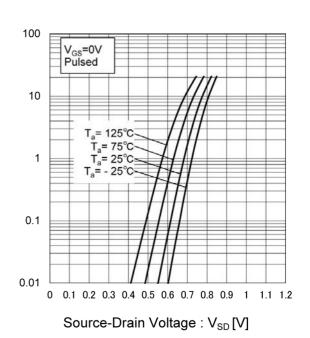


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : Is [A]

## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

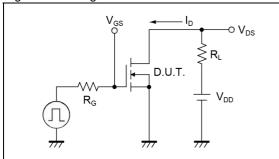


Fig.2-1 Gate Charge Measurement Circuit

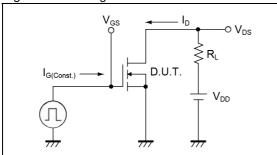


Fig.3-1 Avalanche Measurement Circuit

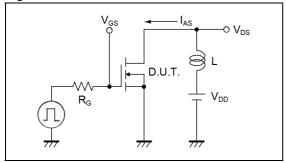


Fig.1-2 Switching Waveforms

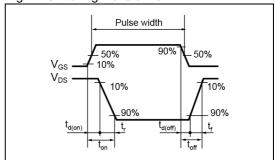


Fig.2-2 Gate Charge Waveform

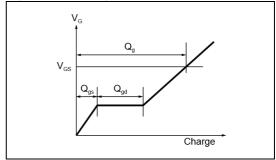
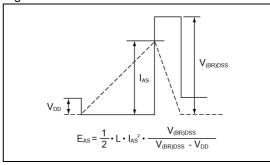
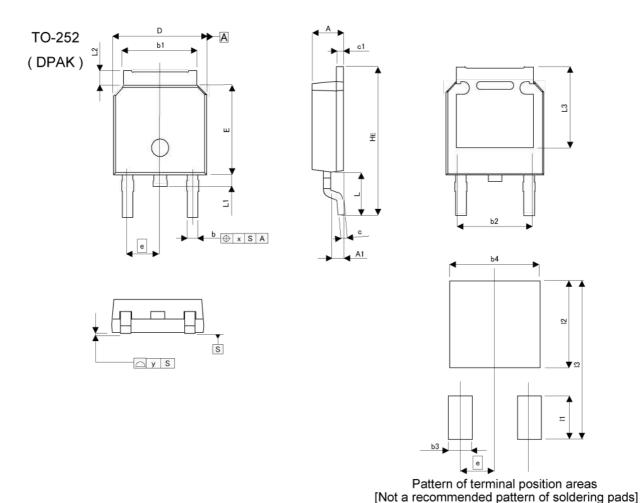


Fig.3-2 Avalanche Waveform



# Dimensions



**MILIMETERS INCHES** DIM MIN MAX MIN MAX 0.083 2.10 2.30 0.091 Α A1 0.70 1.10 0.028 0.043 b 0.65 0.85 0.026 0.033 0.213 5.10 0.201 5.40 b1 b2 5.10 0.201 0.40 0.60 0.016 0.024 C 0.40 0.60 0.016 0.024 c1 0.252 D 6.40 6.80 0.268 е 6.00 0.236 0.252 6.40 E HE 9.50 10.50 0.374 0.413 0.114 0.70 0.028 0.035 L1 0.90 0.70 0.028 0.051 L2 1.30 L3 0.10 0.004 X 0.10 0.004

DIM	MILIMETERS		INC	HES
DIIVI	MIN	MAX	MIN	MAX
b3	₽	1.10	623	0.043
b4	*	5.40	5,41	0.213
I1 .	<u> </u>	2.90	72	0.114
12	*	5.50	5.00	0.217
13	<u>s</u>	10.50	V21	0.413

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	CL ACCTI	CLASS II b	CLASSⅢ
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSIII

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  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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